

MBRB1545CT

Preferred Device

SWITCHMODE™ Power Rectifier

D²PAK Surface Mount Power Package

The D²PAK Power Rectifier employs the Schottky Barrier principle with a platinum barrier metal. These state-of-the-art devices have the following features:

- Center-Tap Configuration
- Guardring for Stress Protection
- Low Forward Voltage
- 150°C Operating Junction Temperature
- Epoxy Meets UL94, VO at 1/8"
- Short Heat Sink Tab Manufactured — Not Sheared!
- Similar in Size to the Industry Standard TO-220 Package

Mechanical Characteristics

- Case: Epoxy, Molded
- Weight: 1.7 grams (approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds
- Shipped 50 units per plastic tube
- Available in 24 mm Tape and Reel, 800 units per 13" reel by adding a "T4" suffix to the part number
- Marking: B1545T

MAXIMUM RATINGS (Per Leg)

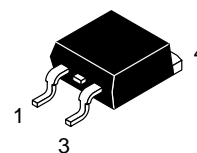
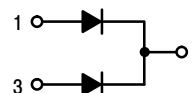
Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V_{RRM} V_{RWM} V_R	45	V
Average Rectified Forward Current (Rated V_R , $T_C = 105^\circ\text{C}$) Total Device	$I_{F(AV)}$	7.5 15	A
Peak Repetitive Forward Current (Rated V_R , Square Wave, 20 kHz, $T_C = 105^\circ\text{C}$)	I_{FRM}	15	A
Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz)	I_{FSM}	150	A
Peak Repetitive Reverse Surge Current (2.0 μs , 1.0 kHz)	I_{RRM}	1.0	A
Storage Temperature Range	T_{stg}	-65 to +175	°C
Operating Junction Temperature	T_J	-65 to +150	°C
Voltage Rate of Change (Rated V_R)	dv/dt	10,000	V/ μs



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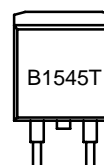
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SCHOTTKY BARRIER RECTIFIER 15 AMPERES 45 VOLTS



D²PAK
CASE 418B
STYLE 3

MARKING DIAGRAM



B1545T = Device Code

ORDERING INFORMATION

Device	Package	Shipping
MBRB1545CT	D ² PAK	50/Rail
MBRB1545CTT4	D ² PAK	800/Tape & Reel

Preferred devices are recommended choices for future use and best overall value.

MBRB1545CT

THERMAL CHARACTERISTICS (Per Leg)

Characteristic	Symbol	Value	Unit
Thermal Resistance — Junction to Case	$R_{\theta JC}$	2.0	$^{\circ}C/W$
— Junction to Ambient (Note 1.)	$R_{\theta JA}$	50	$^{\circ}C/W$

ELECTRICAL CHARACTERISTICS (Per Leg)

Maximum Instantaneous Forward Voltage (Note 2.) ($i_F = 7.5$ Amps, $T_J = 125^{\circ}C$) ($i_F = 15$ Amps, $T_J = 125^{\circ}C$) ($i_F = 15$ Amps, $T_J = 25^{\circ}C$)	V_F	0.57 0.72 0.84	Volts
Maximum Instantaneous Reverse Current (Note 2.) (Rated dc Voltage, $T_J = 125^{\circ}C$) (Rated dc Voltage, $T_J = 25^{\circ}C$)	i_R	15 0.1	mA

- When mounted using minimum recommended pad size on FR-4 board.
- Pulse Test: Pulse Width = 300 μs , Duty Cycle $\leq 2.0\%$.

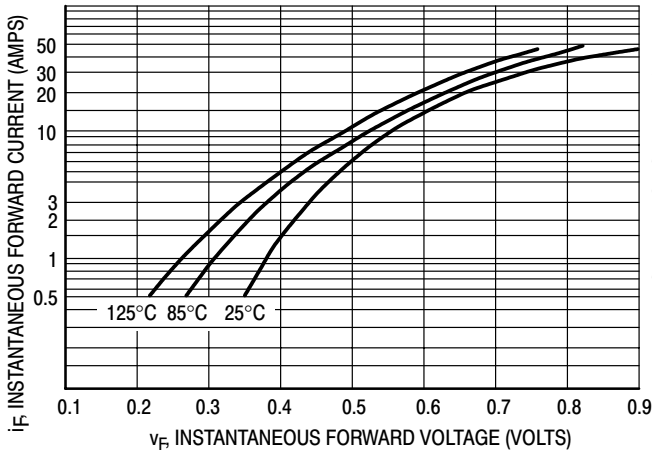


Figure 1. Typical Forward Voltage, Per Leg

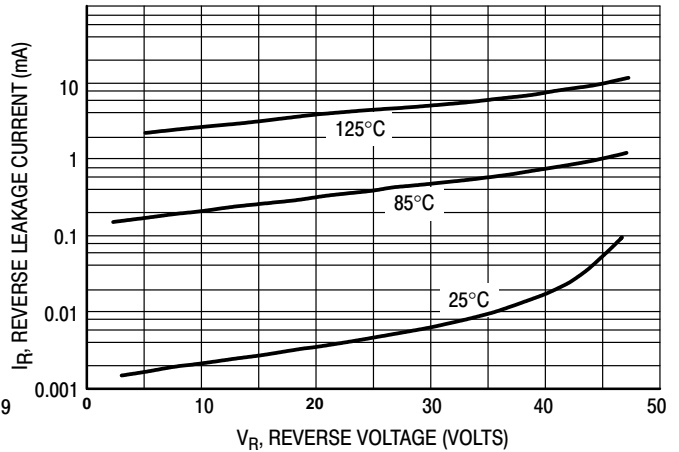


Figure 2. Typical Reverse Current, Per Leg

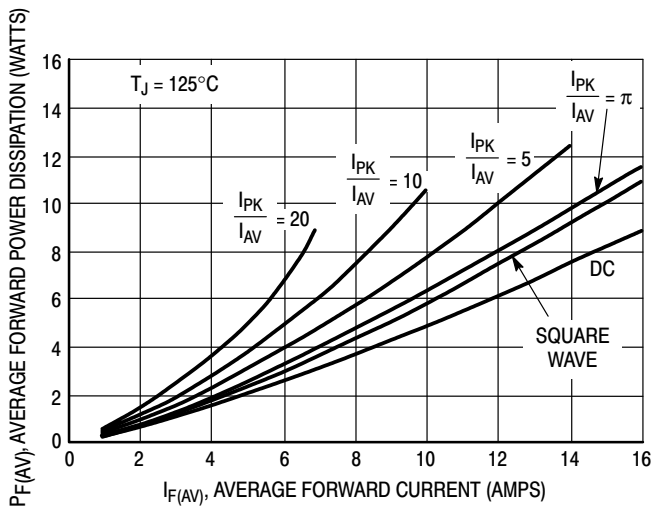


Figure 3. Typical Forward Power Dissipation

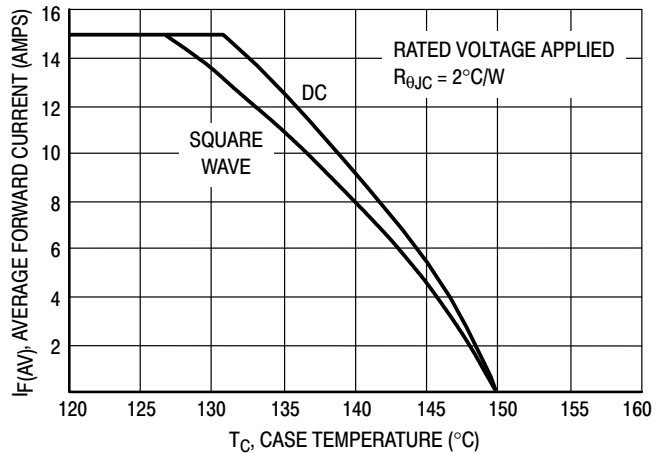


Figure 4. Current Derating, Case

RECOMMENDED PROFILE FOR REFLOW SOLDERING

For any given circuit board, there will be a group of control settings that will give the desired heat pattern. The operator must set temperatures for several heating zones, and a figure for belt speed. Taken together, these control settings make up a heating “profile” for that particular circuit board. On machines controlled by a computer, the computer remembers these profiles from one operating session to the next. Figure 5 shows a typical heating profile for use when soldering the D²PAK to a printed circuit board. This profile will vary among soldering systems but it is a good starting point. Factors that can affect the profile include the type of soldering system in use, density and types of components on the board, type of solder used, and the type of board or substrate material being used. This profile shows temperature versus time. The line on the

graph shows the actual temperature that might be experienced on the surface of a test board at or near a central solder joint. The two profiles are based on a high density and a low density board. The Vitronics SMD310 convection/infrared reflow soldering system was used to generate this profile. The type of solder used was 62/36/2 Tin Lead Silver with a melting point between 177–189°C. When this type of furnace is used for solder reflow work, the circuit boards and solder joints tend to heat first. The components on the board are then heated by conduction. The circuit board, because it has a large surface area, absorbs the thermal energy more efficiently, then distributes this energy to the components. Because of this effect, the main body of a component may be up to 30 degrees cooler than the adjacent solder joints.

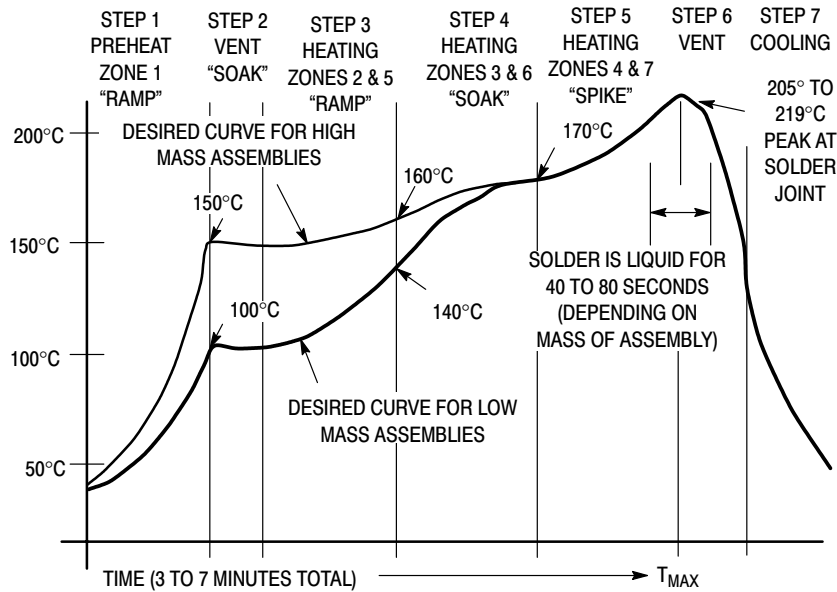
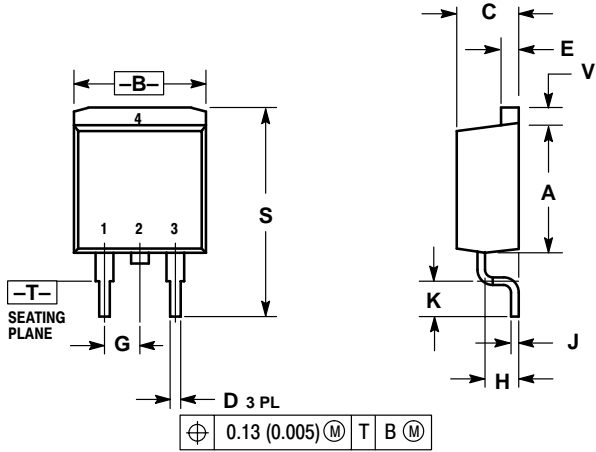


Figure 5. Typical Solder Heating Profile

MBRB1545CT

PACKAGE DIMENSIONS

D²PAK
 PLASTIC
 CASE 418B-03
 ISSUE D



NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.340	0.380	8.64	9.65
B	0.380	0.405	9.65	10.29
C	0.160	0.190	4.06	4.83
D	0.020	0.035	0.51	0.89
E	0.045	0.055	1.14	1.40
G	0.100 BSC		2.54 BSC	
H	0.080	0.110	2.03	2.79
J	0.018	0.025	0.46	0.64
K	0.090	0.110	2.29	2.79
S	0.575	0.625	14.60	15.88
V	0.045	0.055	1.14	1.40

STYLE 1: PIN 1. BASE 2. COLLECTOR 3. EMITTER 4. COLLECTOR	STYLE 2: PIN 1. GATE 2. DRAIN 3. SOURCE 4. DRAIN	STYLE 3: PIN 1. ANODE 2. CATHODE 3. ANODE 4. CATHODE
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Notes

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